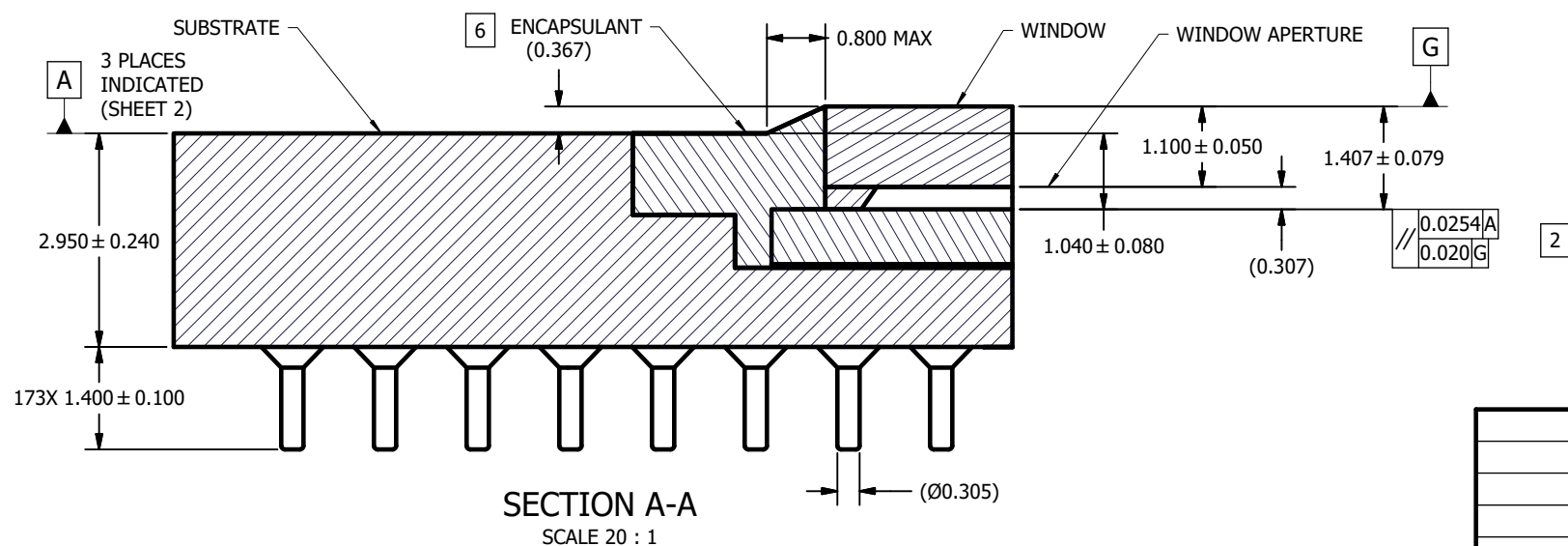
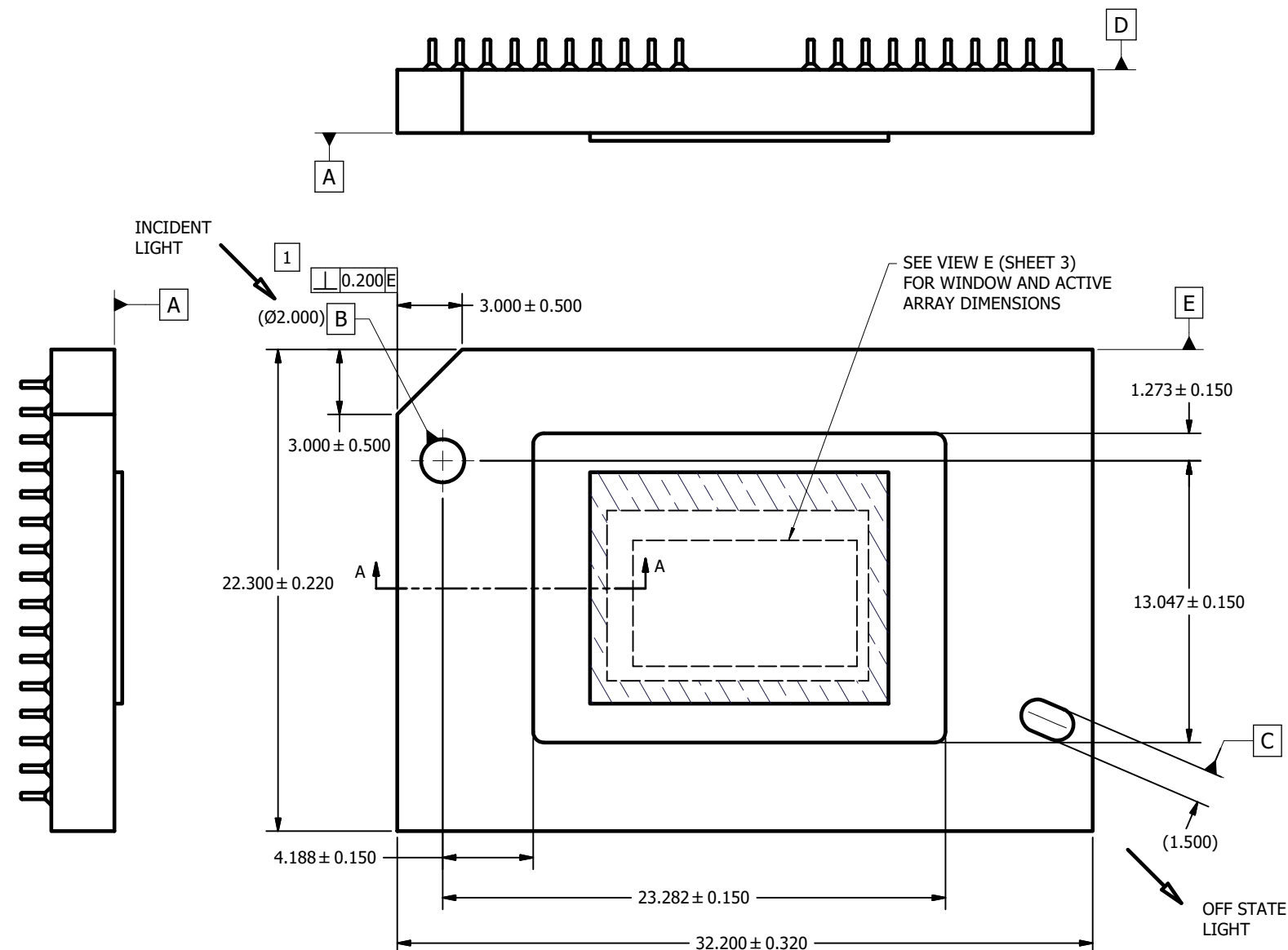


NOTES UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE.
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM VALUE OF 0.8 DEGREES.
- 4 SUBSTRATE SYMBOLIZATION PAD AND PLATING AT BOTTOM OF DATUMS B AND C HOLES TO BE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE.
- 5 BOUNDARY MIRRORS SURROUNDING THE ACTIVE ARRAY.
- 6 MAXIMUM ENCAPSULANT PROFILE SHOWN.
- 7 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULATION SHALL NOT EXCEED 0.2 THICKNESS MAXIMUM.
- 8 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA ABOVE THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA BELOW THE SYMBOLIZATION PAD.

© COPYRIGHT 2024 TEXAS INSTRUMENTS
UN-PUBLISHED. ALL RIGHTS RESERVED.

REVISIONS			
REV	DESCRIPTION	DATE	BY
A	ECO 2209145: INITIAL RELEASE	07/01/2024	HG
B	ECO 2211621: UPDATE POM DIMENSIONS	01/22/2025	PPC



NONE	0314DA
NEXT ASSY	USED ON
APPLICATION	

UNLESS OTHERWISE SPECIFIED

- DIMENSIONS ARE IN MILLIMETERS
- TOLERANCES:

ANGLES $\pm 1^\circ$

2 PLACE DECIMALS ± 0.25

1 PLACE DECIMALS ± 0.50

~~● DIMENSIONS ARE TO BE GIVEN BEFORE PROPOSED~~

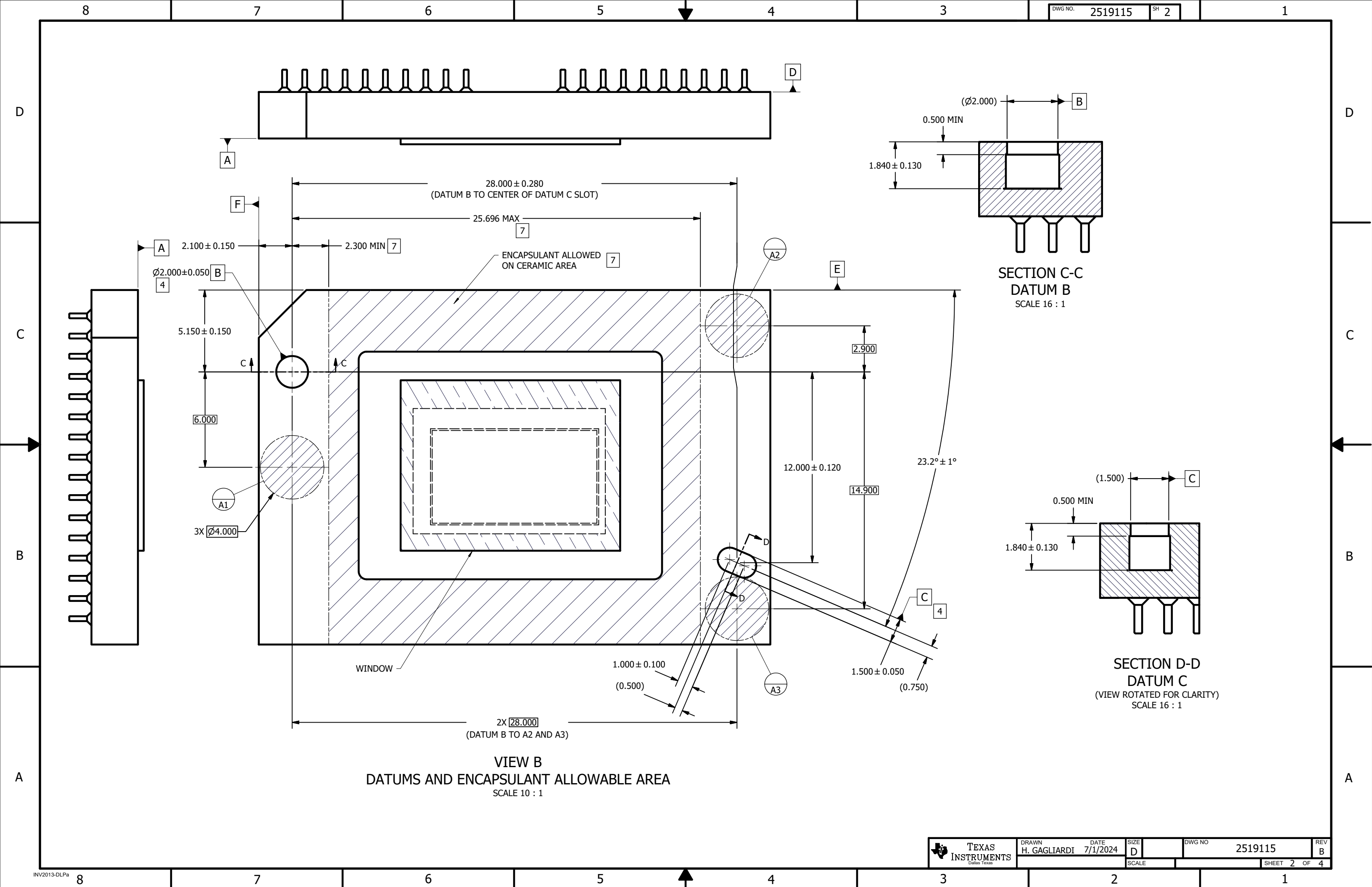
~~● TARGET DIMENSIONS IN ACCORDANCE WITH ASME~~
Y14.5M-1994

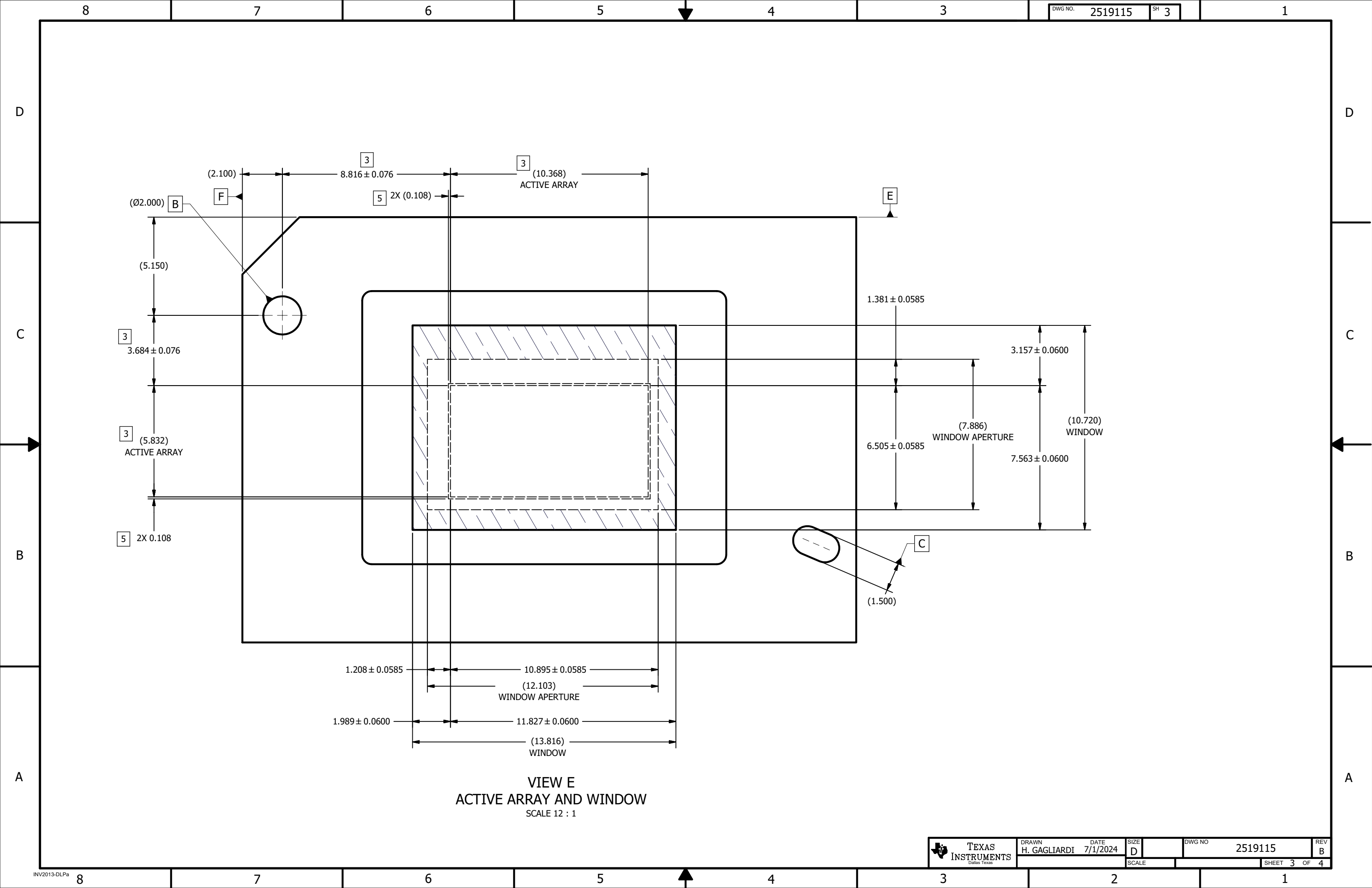
~~● REMOVE ALL BURRS AND CHAMFER~~

● PARENTHEThICAL INFORMATION FOR REFERENCE ONLY

DRAWN	DATE
H. GAGLIARDI	7/1/2024
ENGINEER	
H. GAGLIARDI	7/8/2024
QA/CE	
M. DORAK	7/2/2024
CM	
M. GARCIA	7/1/2024
APPROVED	
1. MCKINLEY	7/3/2024

 TEXAS INSTRUMENTS Dallas Texas	
TITLE ICD, MECHANICAL, DMD .47" SST subLVDS SERIES 460 (FXL PACKAGE)	
SIZE D	DWG NO 2519115
SCALE 4:1	SHEET 1 OF 4





D

D

C

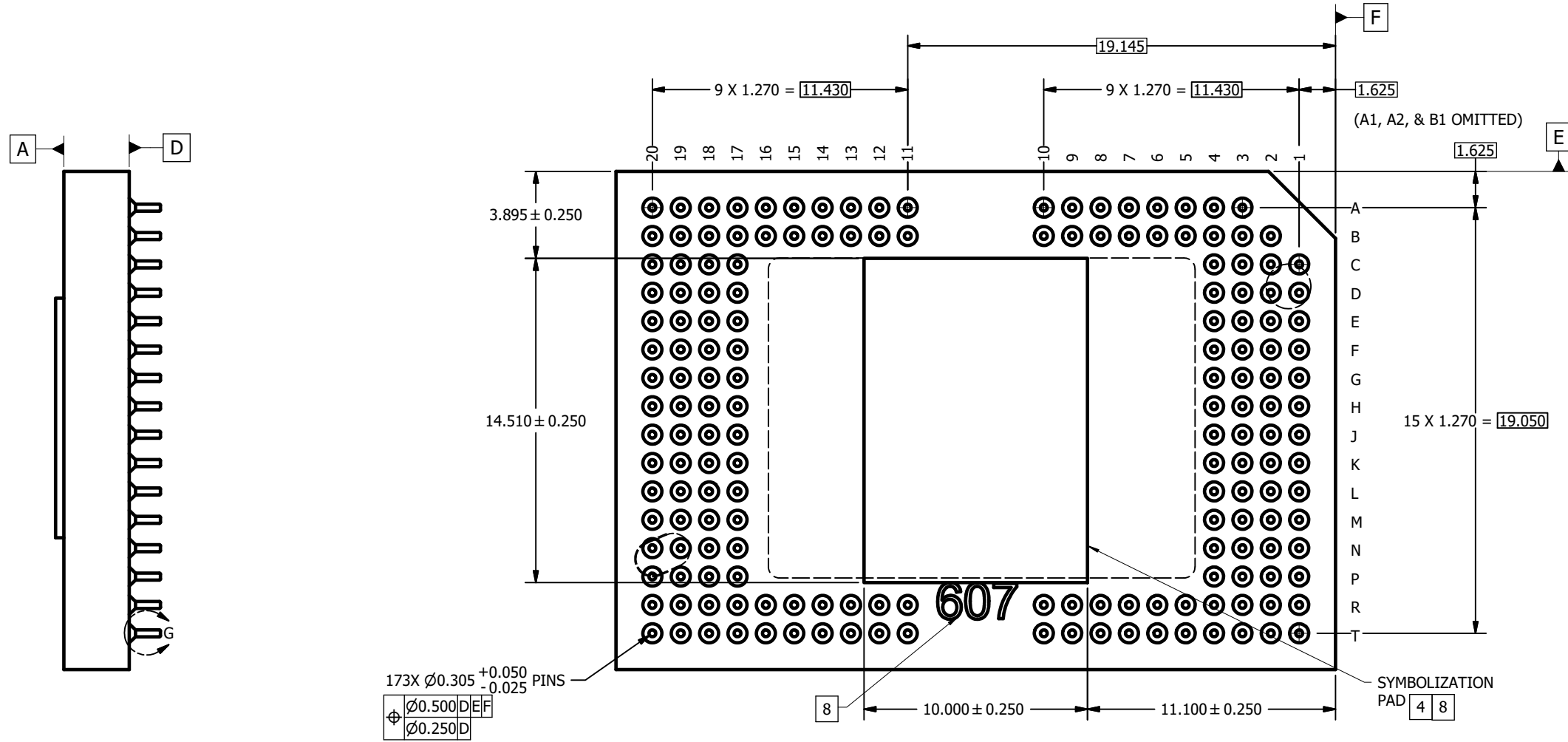
C

B

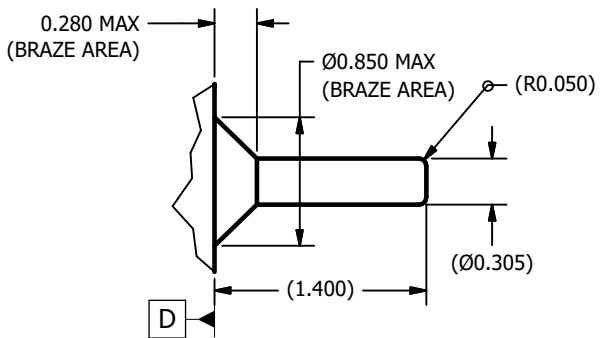
B

A

A



VIEW F
PINS AND SYMBOLIZATION PAD
SCALE 8 : 1



DETAIL G
PIN AND BRAZE DIMENSIONS
173 PLACES
SCALE 40 : 1

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated